

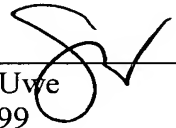
**REMARKS**

With the above amendments, claims 20, 22, 29-31 and 40 have been amended to delete the multiple dependencies and make those claims singly dependent. A marked-up version showing the changes made to those claims is attached for the convenience of the Examiner.

In view of the above, it is believed that the application is in good condition for examination, and the Examiner's early and favorable consideration is respectfully requested. Questions are welcomed by the below-signed attorney for applicants.

Respectfully submitted,

GRIFFIN & SZIPL, P.C.

  
\_\_\_\_\_  
SZIPL, Joerg-Uwe  
Reg. No. 31,799

GRIFFIN & SZIPL, PC  
Suite PH-1  
2300 Ninth Street, South  
Arlington, VA 22204

Telephone: (703) 979-5700  
Facsimile: (703) 979-7429  
Customer No.: 24203

10030699-12004

**VERSION WITH MARKINGS TO SHOW CLAIM CHANGES MADE**

20. (Amended) A photosensitive element roll according to ~~any one of Claims 1 to 19~~Claim 1, wherein the above photosensitive element is wound up or rolled around a core.
22. (Amended) A process for preparing a resist pattern which comprises laminating the photosensitive element according to ~~any one of Claims 1 to 20~~Claim 1 to a substrate for forming a circuit so that the photosensitive resin composition layer is closely contacted to the substrate, irradiating imagewise active light to photocure the exposed portion, and removing an unexposed portion by development.
29. (Amended) The resist pattern according to ~~any one of Claims 24 to 28~~Claim 24, wherein a width of the resist pattern is 1  $\mu\text{m}$  or more.
30. (Amended) The resist pattern according to ~~any one of Claims 24 to 28~~Claim 24, wherein a height of the resist pattern is 1 to 150  $\mu\text{m}$ .
31. (Amended) The resist pattern laminated substrate which comprises the resist pattern according to ~~any one of Claims 24 to 28~~Claim 24, wherein it is formed on a substrate for preparing a circuit.
40. (Amended) The wiring pattern according to ~~any one of Claims 34 to 38~~Claim 34, wherein a height of the wiring pattern is 0.01 to 200  $\mu\text{m}$ .